



Printed Circuit Boards
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

Seite:

PRINTED CIRCUIT BOARDS

01

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 110 FR4 70 L50.35 P10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_110_FR4_70_L50.35_p10

Layers	in μ	Material	Build-Up	Assembly	
Layer-1	70 μ	Copper			
	100 μ	Prepreg			(100 μ PrePreg-Type: 2125)
	100 μ	Prepreg			
Layer-2	35 μ	Copper			
	500 μ	L-FR4			
Layer-3	35 μ	Copper			
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-99	70 μ	Copper			

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